# IGBT

High speed 5 FAST IGBT in TRENCHSTOP$^{TM}$ 5 technology

# IGW50N65F5A

650V IGBT
High speed switching series fifth generation

## Data sheet

## Industrial Power Control

# High speed 5 FAST IGBT in TRENCHSTOP™ 5 technology

**Features and Benefits:**

High speed F5 technology offering
• Best-in-Class efficiency in hard switching and resonant topologies
• 650V breakdown voltage
• Low gate charge $Q_G$
• Maximum junction temperature 175°C
• Qualified according to AEC-Q101
• Green package (RoHS compliant)
• Complete product spectrum and PSpice Models:
http://www.infineon.com/igbt/
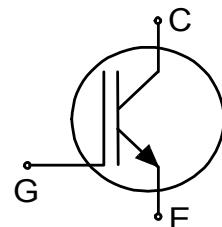
**Applications:**

• Battery charger
• DC/DC converter

**Package pin definition:**

• Pin 1 - gate
• Pin 2 & backside - collector
• Pin 3 - emitter

## Key Performance and Package Parameters

| Type | $V_{CE}$ | $I_C$ | $V_{CEsat}$, $T_{vj}$=25°C | $T_{vjmax}$ | Marking | Package |
|---|---|---|---|---|---|---|
| IGW50N65F5A | 650V | 50A | 1.66V | 175°C | G50EF5A | PG-TO247-3 |

**Table of Contents**

## Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

| Parameter | Symbol | Value | Unit |
|---|---|---|---|
| Collector-emitter voltage, $T_{vj} \geq 25°C$ | $V_{CE}$ | 650 | V |
| DC collector current, limited by $T_{vjmax}$<br>$T_C$ = 25°C value limited by bondwire<br>$T_C$ = 100°C | $I_C$ | 80.0<br>53.5 | A |
| Pulsed collector current, $t_p$ limited by $T_{vjmax}$[1] | $I_{Cpuls}$ | 150.0 | A |
| Turn off safe operating area<br>$V_{CE} \leq 650V$, $T_{vj} \leq 175°C$, $t_p$ = 1µs[1] | - | 150.0 | A |
| Gate-emitter voltage<br>Transient Gate-emitter voltage ($t_p \leq 10µs$, D < 0.010) | $V_{GE}$ | ±20<br>±30 | V |
| Power dissipation $T_C$ = 25°C<br>Power dissipation $T_C$ = 100°C | $P_{tot}$ | 270.0<br>136.0 | W |
| Operating junction temperature | $T_{vj}$ | -40...+175 | °C |
| Storage temperature | $T_{stg}$ | -55...+150 | °C |
| Soldering temperature,[2]<br>wave soldering 1.6mm (0.063in.) from case for 10s | | 260 | °C |
| Mounting torque, M3 screw<br>Maximum of mounting processes: 3 | $M$ | 0.6 | Nm |

## Thermal Resistance

| Parameter | Symbol | Conditions | Max. Value | Unit |
|---|---|---|---|---|
| **Characteristic** | | | | |
| IGBT thermal resistance,<br>junction - case | $R_{th(j-c)}$ | | 0.55 | K/W |
| Thermal resistance<br>junction - ambient | $R_{th(j-a)}$ | | 40 | K/W |

## Electrical Characteristic, at $T_{vj}$ = 25°C, unless otherwise specified

| Parameter | Symbol | Conditions | Value min. | Value typ. | Value max. | Unit |
|---|---|---|---|---|---|---|
| **Static Characteristic** | | | | | | |
| Collector-emitter breakdown voltage | $V_{(BR)CES}$ | $V_{GE}$ = 0V, $I_C$ = 0.20mA | 650 | - | - | V |
| Collector-emitter saturation voltage | $V_{CEsat}$ | $V_{GE}$ = 15.0V, $I_C$ = 50.0A<br>$T_{vj}$ = 25°C<br>$T_{vj}$ = 125°C<br>$T_{vj}$ = 175°C | -<br>-<br>- | 1.66<br>1.90<br>2.03 | 2.10<br>-<br>- | V |
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $I_C$ = 0.40mA, $V_{CE}$ = $V_{GE}$ | 3.2 | 4.0 | 4.8 | V |
| Zero gate voltage collector current | $I_{CES}$ | $V_{CE}$ = 650V, $V_{GE}$ = 0V<br>$T_{vj}$ = 25°C<br>$T_{vj}$ = 175°C | -<br>- | -<br>600.0 | 40.0<br>- | µA |
| Gate-emitter leakage current | $I_{GES}$ | $V_{CE}$ = 0V, $V_{GE}$ = 20V | - | - | 100 | nA |
| Transconductance | $g_{fs}$ | $V_{CE}$ = 20V, $I_C$ = 50.0A | - | 62.0 | - | S |

[1] Defined by design. Not subject to production test.
[2] Package not recommended for surface mount applications

**Electrical Characteristic, at $T_{vj}$ = 25°C, unless otherwise specified**

| Parameter | Symbol | Conditions | Value | | | Unit |
|---|---|---|---|---|---|---|
| | | | min. | typ. | max. | |
| **Dynamic Characteristic** | | | | | | |
| Input capacitance | $C_{ies}$ | $V_{CE}$ = 25V, $V_{GE}$ = 0V, f = 1MHz | - | 2800 | - | pF |
| Output capacitance | $C_{oes}$ | | - | 51 | - | |
| Reverse transfer capacitance | $C_{res}$ | | - | 11 | - | |
| Gate charge | $Q_G$ | $V_{CC}$ = 520V, $I_C$ = 50.0A, $V_{GE}$ = 15V | - | 108.0 | - | nC |
| Internal emitter inductance measured 5mm (0.197 in.) from case | $L_E$ | | - | 13.0 | - | nH |

**Switching Characteristic, Inductive Load**

| Parameter | Symbol | Conditions | Value | | | Unit |
|---|---|---|---|---|---|---|
| | | | min. | typ. | max. | |
| **IGBT Characteristic, at $T_{vj}$ = 25°C** | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $T_{vj}$ = 25°C, $V_{CC}$ = 400V, $I_C$ = 25.0A, $V_{GE}$ = 0.0/15.0V, $R_{G(on)}$ = 12.0Ω, $R_{G(off)}$ = 12.0Ω, $L\sigma$ = 30nH, $C\sigma$ = 30pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 21 | - | ns |
| Rise time | $t_r$ | | - | 12 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 156 | - | ns |
| Fall time | $t_f$ | | - | 6 | - | ns |
| Turn-on energy | $E_{on}$ | | - | 0.49 | - | mJ |
| Turn-off energy | $E_{off}$ | | - | 0.14 | - | mJ |
| Total switching energy | $E_{ts}$ | | - | 0.63 | - | mJ |
| Turn-on delay time | $t_{d(on)}$ | $T_{vj}$ = 25°C, $V_{CC}$ = 400V, $I_C$ = 6.0A, $V_{GE}$ = 0.0/15.0V, $R_{G(on)}$ = 12.0Ω, $R_{G(off)}$ = 12.0Ω, $L\sigma$ = 30nH, $C\sigma$ = 30pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 19 | - | ns |
| Rise time | $t_r$ | | - | 4 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 173 | - | ns |
| Fall time | $t_f$ | | - | 10 | - | ns |
| Turn-on energy | $E_{on}$ | | - | 0.10 | - | mJ |
| Turn-off energy | $E_{off}$ | | - | 0.03 | - | mJ |
| Total switching energy | $E_{ts}$ | | - | 0.13 | - | mJ |

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**Switching Characteristic, Inductive Load**

| Parameter | Symbol | Conditions | Value | | | Unit |
|---|---|---|---|---|---|---|
| | | | min. | typ. | max. | |
| **IGBT Characteristic, at $T_{vj}$ = 150°C** | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $T_{vj}$ = 150°C, $V_{CC}$ = 400V, $I_C$ = 25.0A, $V_{GE}$ = 0.0/15.0V, $R_{G(on)}$ = 12.0Ω, $R_{G(off)}$ = 12.0Ω, $L\sigma$ = 30nH, $C\sigma$ = 30pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 21 | - | ns |
| Rise time | $t_r$ | | - | 14 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 191 | - | ns |
| Fall time | $t_f$ | | - | 5 | - | ns |
| Turn-on energy | $E_{on}$ | | - | 0.68 | - | mJ |
| Turn-off energy | $E_{off}$ | | - | 0.25 | - | mJ |
| Total switching energy | $E_{ts}$ | | - | 0.93 | - | mJ |
| Turn-on delay time | $t_{d(on)}$ | $T_{vj}$ = 150°C, $V_{CC}$ = 400V, $I_C$ = 6.0A, $V_{GE}$ = 0.0/15.0V, $R_{G(on)}$ = 12.0Ω, $R_{G(off)}$ = 12.0Ω, $L\sigma$ = 30nH, $C\sigma$ = 30pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 18 | - | ns |
| Rise time | $t_r$ | | - | 5 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 229 | - | ns |
| Fall time | $t_f$ | | - | 12 | - | ns |
| Turn-on energy | $E_{on}$ | | - | 0.18 | - | mJ |
| Turn-off energy | $E_{off}$ | | - | 0.06 | - | mJ |
| Total switching energy | $E_{ts}$ | | - | 0.24 | - | mJ |

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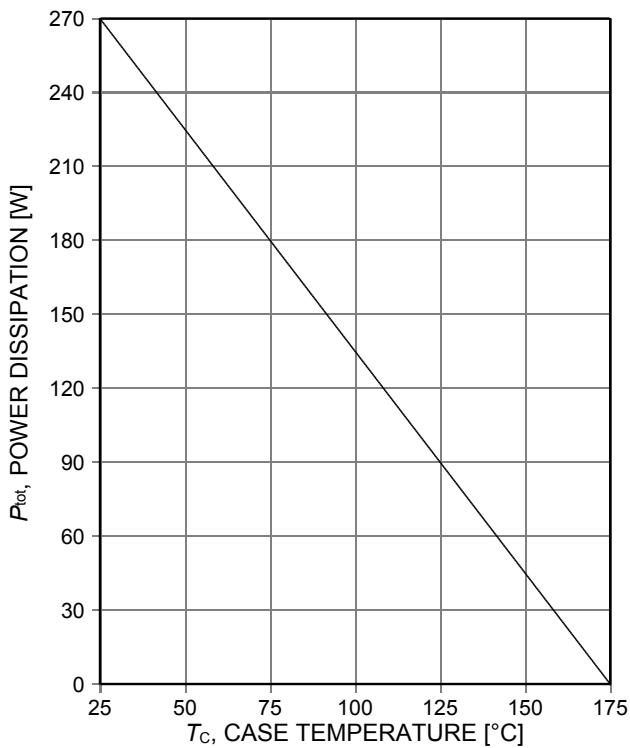
Figure 1. **Power dissipation as a function of case temperature**
($T_{vj}$≤175°C)
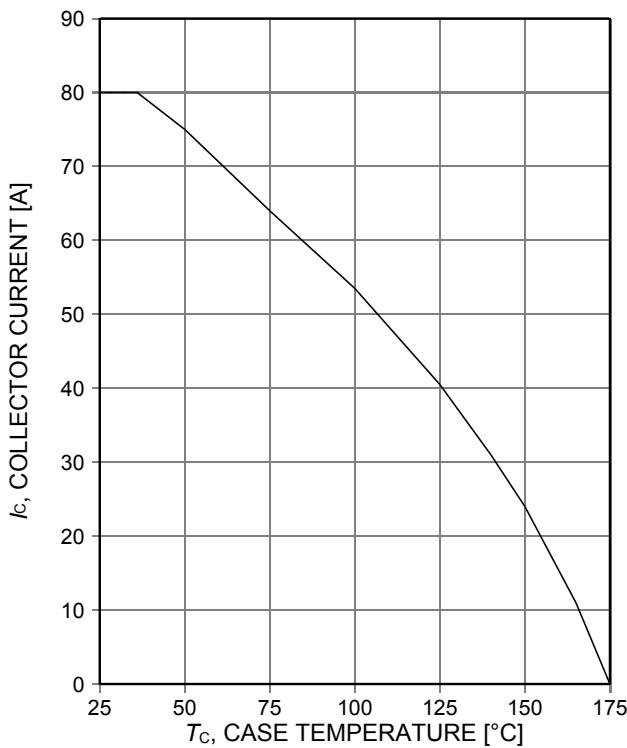


Figure 2. **Collector current as a function of case temperature**
($V_{GE}$≥15V, $T_{vj}$≤175°C)
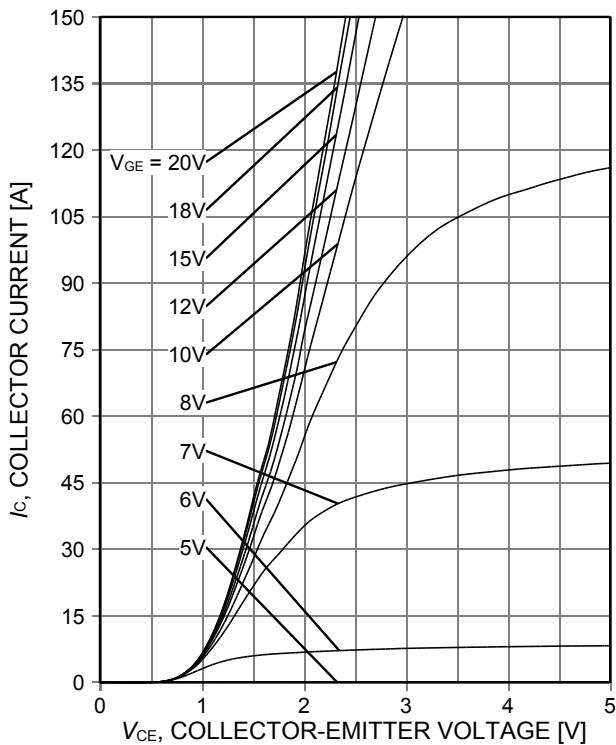


Figure 3. **Typical output characteristic**
($T_{vj}$=25°C)
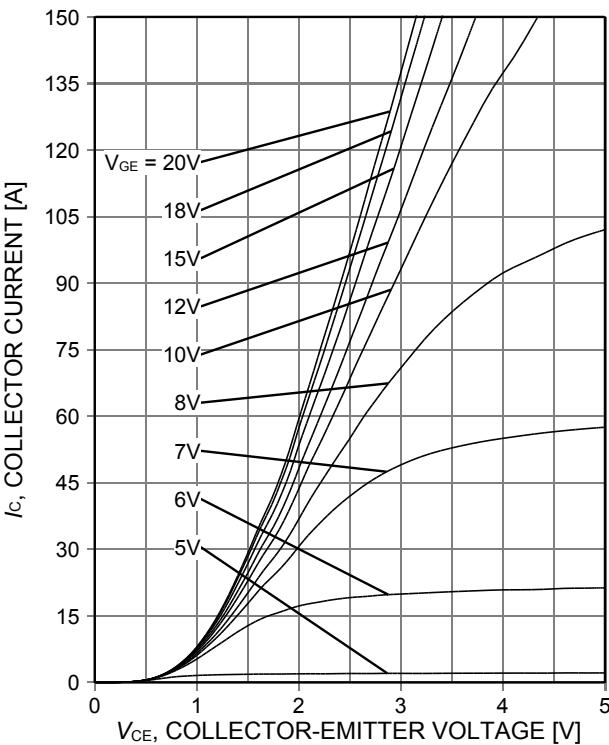


Figure 4. **Typical output characteristic**
($T_{vj}$=150°C)

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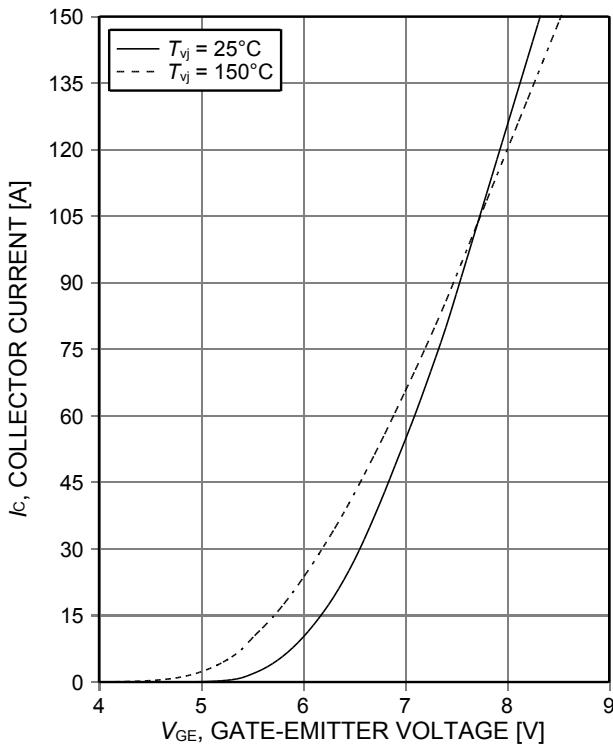
Figure 5. **Typical transfer characteristic**
($V_{CE}$=20V)
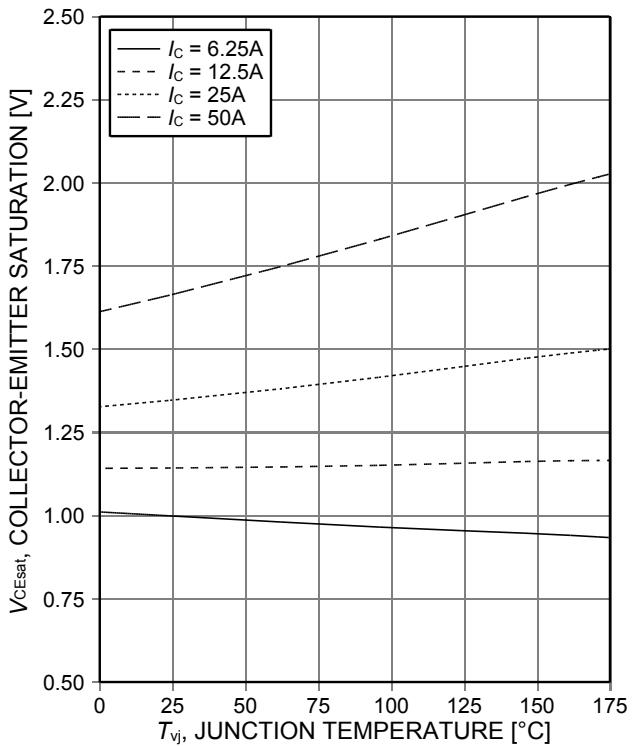


Figure 6. **Typical collector-emitter saturation voltage as a function of junction temperature**
($V_{GE}$=15V)
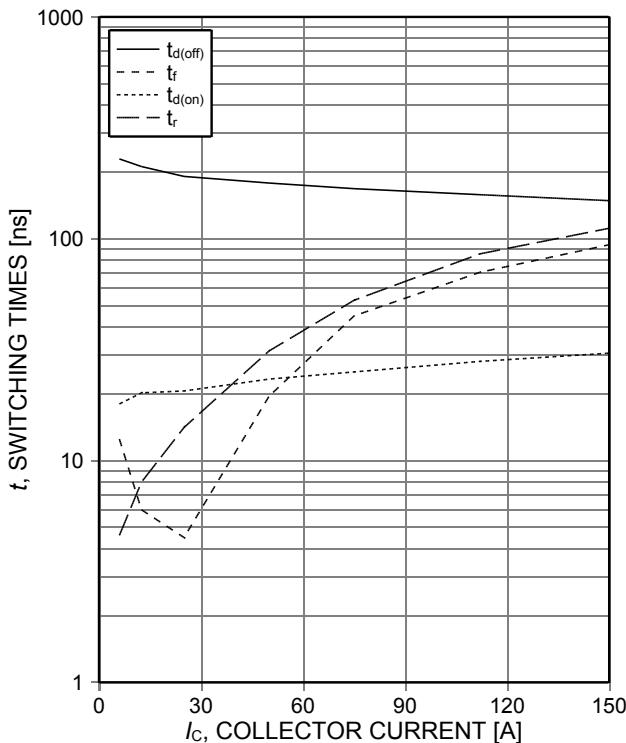


Figure 7. **Typical switching times as a function of collector current**
(inductive load, $T_{vj}$=150°C, $V_{CE}$=400V, $V_{GE}$=0/15V, $R_{G(on)}$=12Ω, $R_{G(off)}$=12Ω, dynamic test circuit in Figure E)
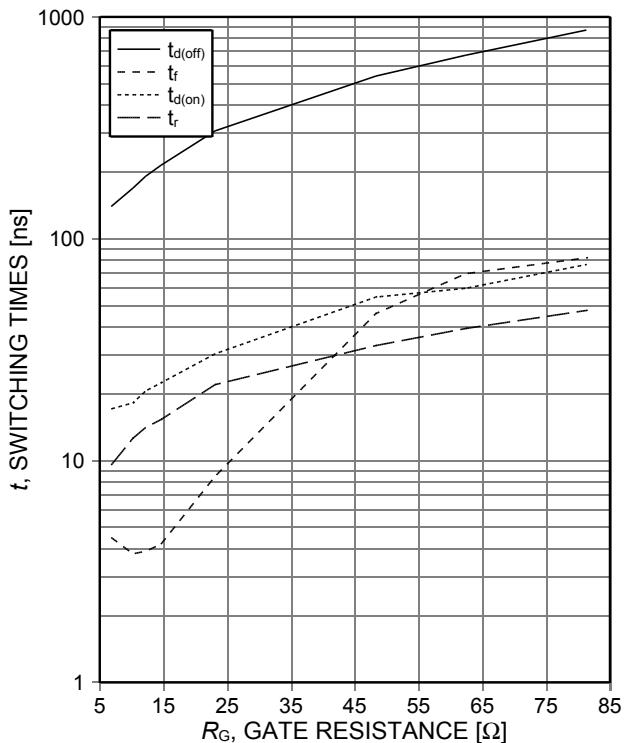


Figure 8. **Typical switching times as a function of gate resistance**
(inductive load, $T_{vj}$=150°C, $V_{CE}$=400V, $V_{GE}$=0/15V, $I_C$=25A, dynamic test circuit in Figure E)

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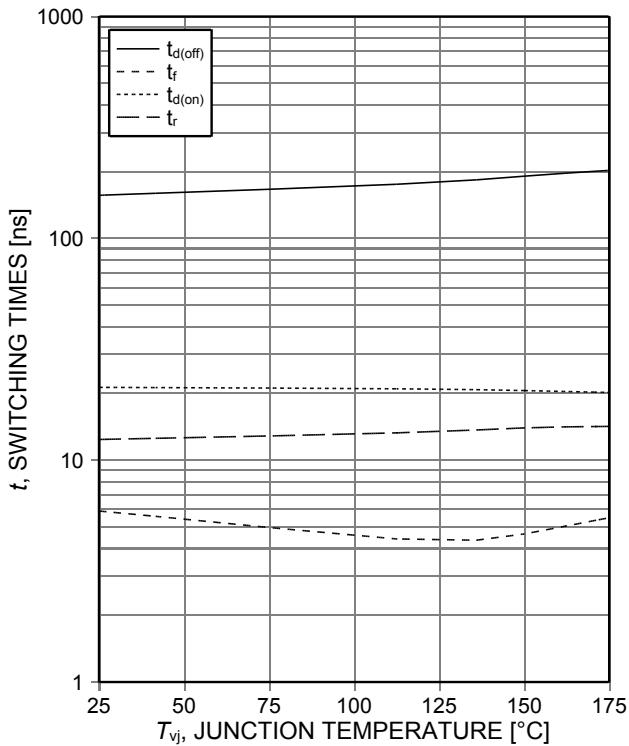
Figure 9. **Typical switching times as a function of junction temperature**
(inductive load, $V_{CE}$=400V, $V_{GE}$=0/15V, $I_C$=25A, $R_{G(on)}$=12Ω, $R_{G(off)}$=12Ω, dynamic test circuit in Figure E)
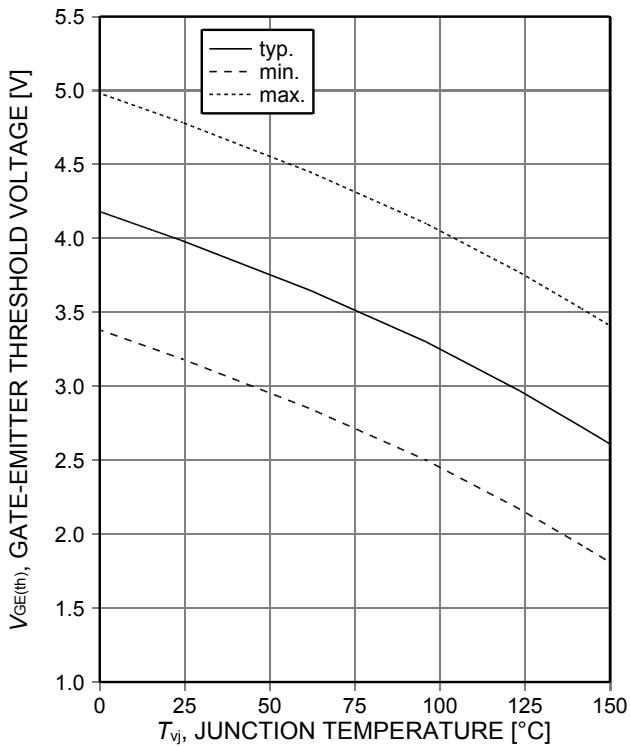


Figure 10. **Gate-emitter threshold voltage as a function of junction temperature**
($I_C$=0.4mA)
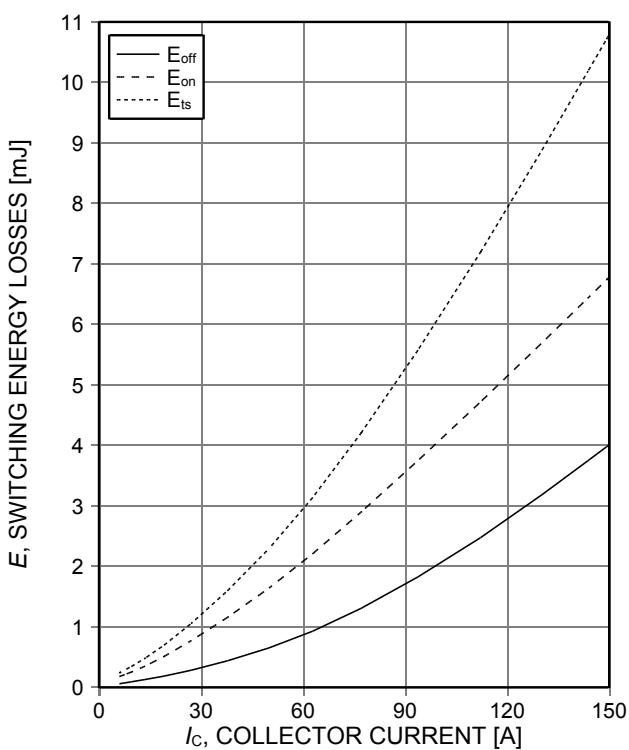


Figure 11. **Typical switching energy losses as a function of collector current**
(inductive load, $T_{vj}$=150°C, $V_{CE}$=400V, $V_{GE}$=0/15V, $R_{G(on)}$=12Ω, $R_{G(off)}$=12Ω, dynamic test circuit in Figure E)
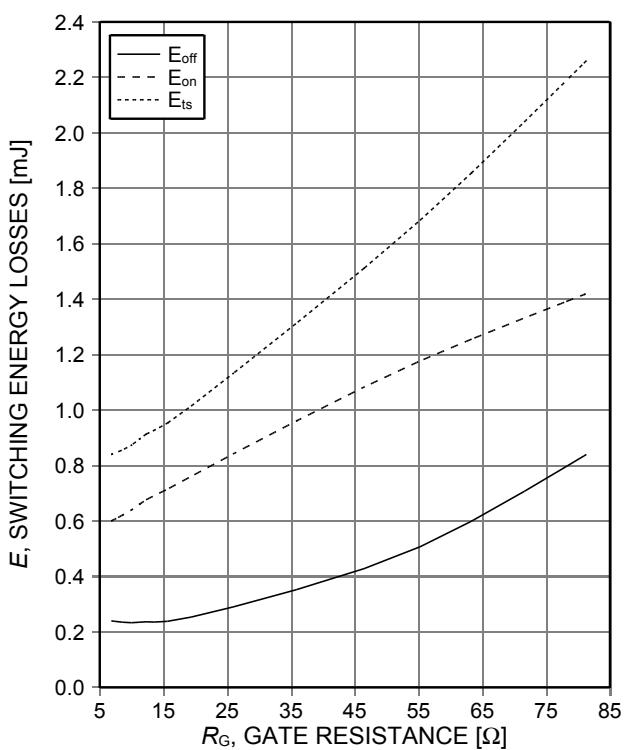


Figure 12. **Typical switching energy losses as a function of gate resistance**
(inductive load, $T_{vj}$=150°C, $V_{CE}$=400V, $V_{GE}$=0/15V, $I_C$=25A, dynamic test circuit in Figure E)

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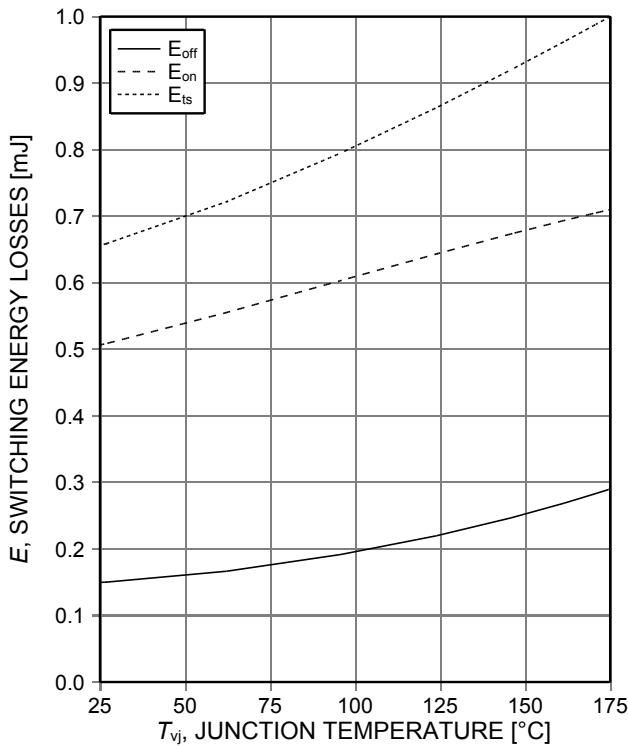
Figure 13. **Typical switching energy losses as a function of junction temperature** (inductive load, $V_{CE}$=400V, $V_{GE}$=0/15V, $I_C$=25A, $R_{G(on)}$=12Ω, $R_{G(off)}$=12Ω, dynamic test circuit in Figure E)
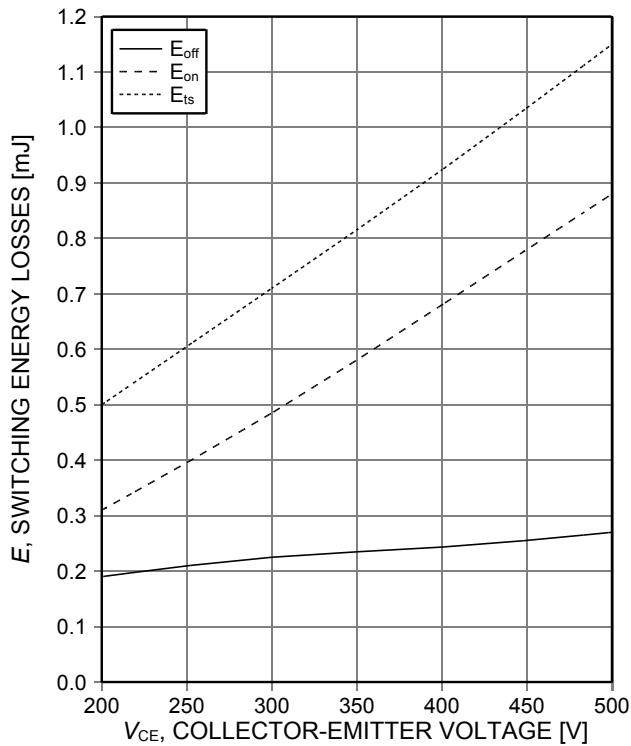


Figure 14. **Typical switching energy losses as a function of collector emitter voltage** (inductive load, $T_{vj}$=150°C, $V_{GE}$=0/15V, $I_C$=25A, $R_{G(on)}$=12Ω, $R_{G(off)}$=12Ω, dynamic test circuit in Figure E)
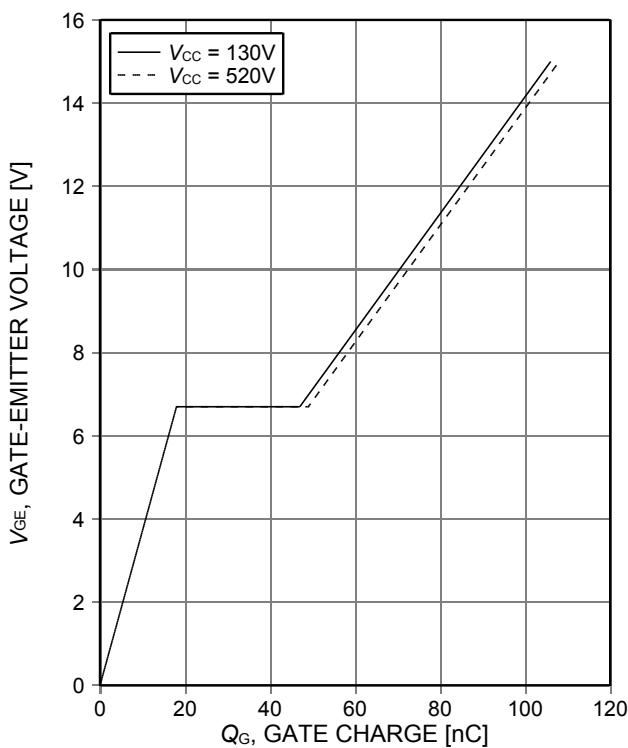


Figure 15. **Typical gate charge** ($I_C$=50A)
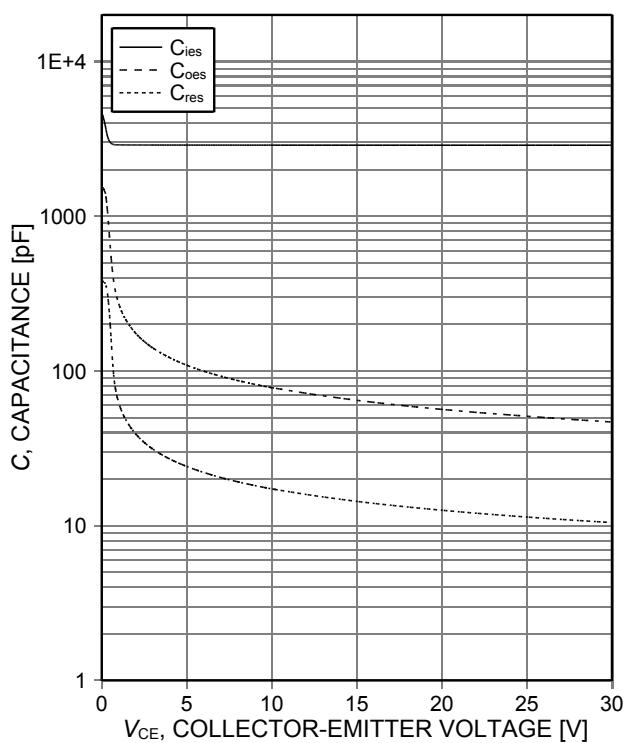


Figure 16. **Typical capacitance as a function of collector-emitter voltage** ($V_{GE}$=0V, f=1MHz)
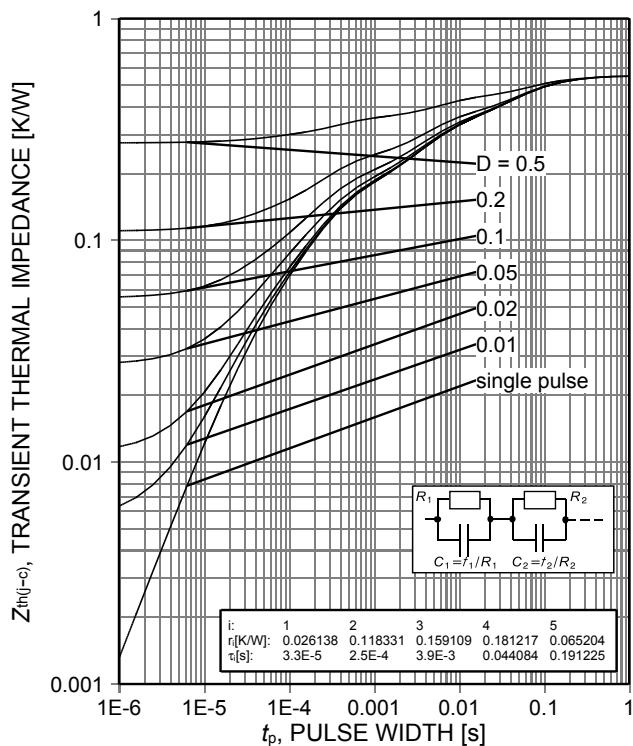
Figure 17. **IGBT transient thermal impedance**
$(D=t_p/T)$

## PG-TO247-3
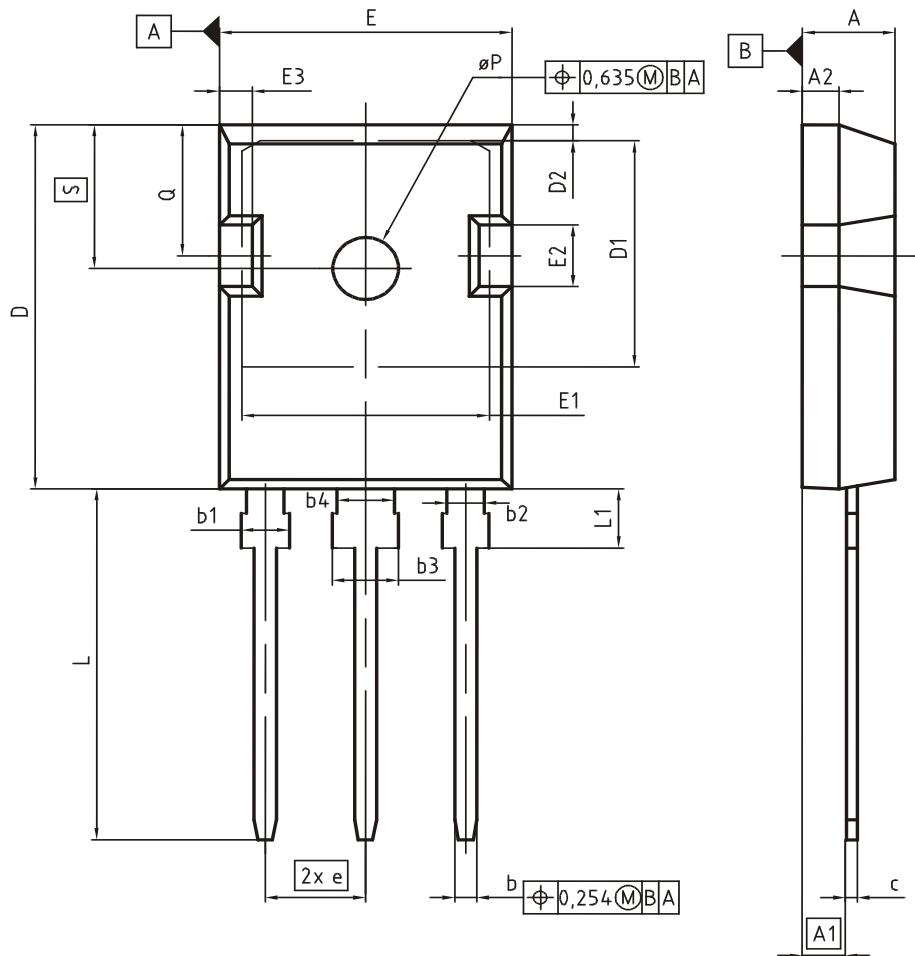


| DIM | MILLIMETERS | | INCHES | |
|-----|------|------|------|------|
| | MIN | MAX | MIN | MAX |
| A | 4.83 | 5.21 | 0.190 | 0.205 |
| A1 | 2.27 | 2.54 | 0.089 | 0.100 |
| A2 | 1.85 | 2.16 | 0.073 | 0.085 |
| b | 1.07 | 1.33 | 0.042 | 0.052 |
| b1 | 1.90 | 2.41 | 0.075 | 0.095 |
| b2 | 1.90 | 2.16 | 0.075 | 0.085 |
| b3 | 2.87 | 3.38 | 0.113 | 0.133 |
| b4 | 2.87 | 3.13 | 0.113 | 0.123 |
| c | 0.55 | 0.68 | 0.022 | 0.027 |
| D | 20.80 | 21.10 | 0.819 | 0.831 |
| D1 | 16.25 | 17.65 | 0.640 | 0.695 |
| D2 | 0.95 | 1.35 | 0.037 | 0.053 |
| E | 15.70 | 16.13 | 0.618 | 0.635 |
| E1 | 13.10 | 14.15 | 0.516 | 0.557 |
| E2 | 3.68 | 5.10 | 0.145 | 0.201 |
| E3 | 1.00 | 2.60 | 0.039 | 0.102 |
| e | 5.44 (BSC) | | 0.214 (BSC) | |
| N | 3 | | 3 | |
| L | 19.80 | 20.32 | 0.780 | 0.800 |
| L1 | 4.10 | 4.47 | 0.161 | 0.176 |
| øP | 3.50 | 3.70 | 0.138 | 0.146 |
| Q | 5.49 | 6.00 | 0.216 | 0.236 |
| S | 6.04 | 6.30 | 0.238 | 0.248 |

**DOCUMENT NO.**
Z8B00003327

**SCALE**

**EUROPEAN PROJECTION**

**ISSUE DATE**
09-07-2010

**REVISION**
05
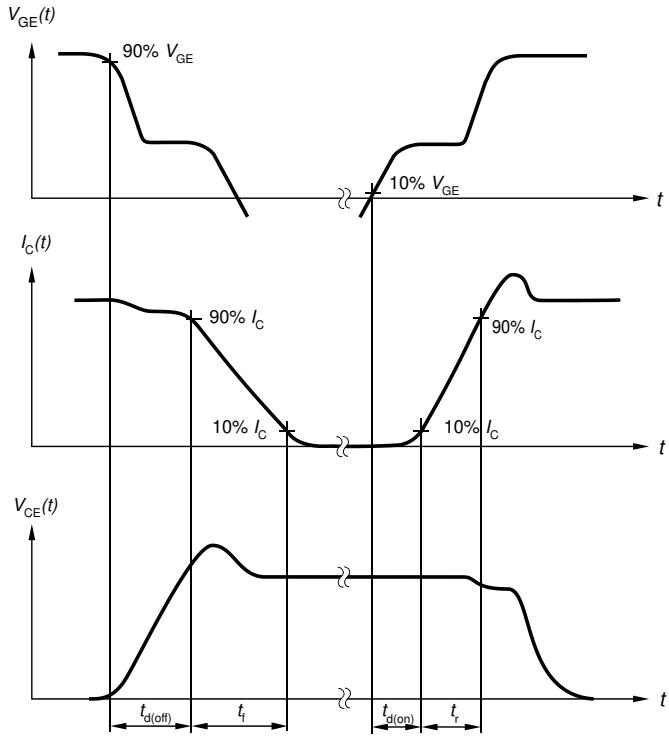
Figure A. **Definition of switching times**
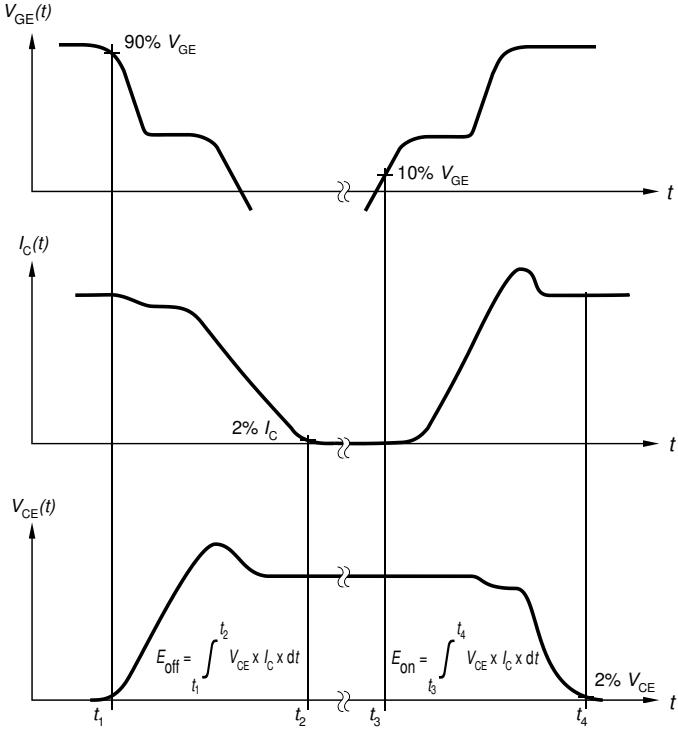


Figure B. **Definition of switching losses**

$$E_{off} = \int_{t_1}^{t_2} V_{CE} \times I_C \times dt$$

$$E_{on} = \int_{t_3}^{t_4} V_{CE} \times I_C \times dt$$



$$t_{rr} = t_a + t_b$$
$$Q_{rr} = Q_a + Q_b$$
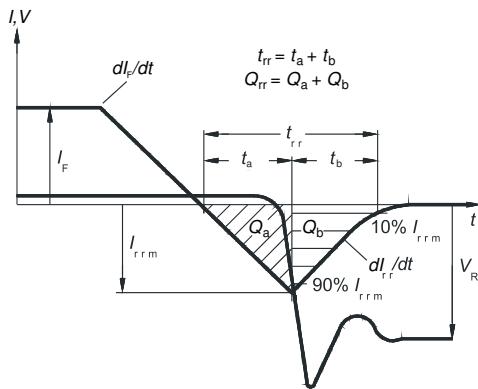
Figure C. **Definition of diode switching characteristics**
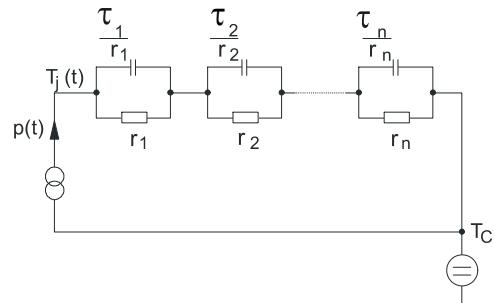


Figure D. **Thermal equivalent circuit**
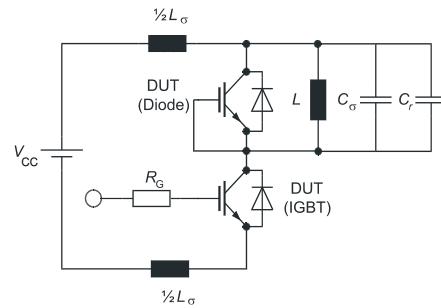


Figure E. **Dynamic test circuit**
Parasitic inductance $L_\sigma$,
parasitic capacitor $C_\sigma$,
relief capacitor $C_r$,
(only for ZVT switching)

Rev. 2.1,  2015-01-15

Revision History

IGW50N65F5A

Revision: 2015-01-15, Rev. 2.1

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|---|---|---|
| 2.1 | 2015-01-15 | Final data sheet |

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